



Material Content Data Sheet



Sales Product Name		BGA 123L4 E6327		Issued		22. January 2018		
MA#		MA001680298						
Package		PG-TSLP-4-11		Weight*		0.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.082	16.99	16.99	169865	169865
bumps	non noble metal	copper	7440-50-8	0.005	0.95	0.95	9459	9459
leadframe	non noble metal	nickel	7440-02-0	0.174	36.16	36.16	361509	361509
encapsulation	organic material	carbon black	1333-86-4	0.001	0.21		2104	
	plastics	epoxy resin	-	0.029	6.10		61012	
	inorganic material	silicondioxide	60676-86-0	0.172	35.77	42.08	357654	420770
leadfinish	noble metal	gold	7440-57-5	0.006	1.25	1.25	12524	12524
plating	noble metal	silver	7440-22-4	0.010	2.04	2.04	20449	20449
ubm	non noble metal	tungsten	7440-33-7	0.000	0.00		27	
	non noble metal	titanium	7440-32-6	0.000	0.00		50	
	non noble metal	copper	7440-50-8	0.000	0.01	0.01	144	221
solder	noble metal	silver	7440-22-4	0.000	0.01		119	
	non noble metal	tin	7440-31-5	0.002	0.51	0.52	5084	5203
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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